

SLOVENSKI STANDARD

SIST EN IEC 62680-1-2:2019

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Nadomešča:

SIST EN 62680-1-2:2018

Vmesniki univerzalnega serijskega vodila za prenos podatkov in napajanje - 1-2. del: Skupne komponente - Specifikacija zagotavljanja napajanja prek USB (IEC 62680-1-2:2018)

Universal Serial Bus interfaces for data and power - Part 1-2: Common components - USB Power Delivery Specification (IEC 62680-1-2:2018)

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Schnittstellen des Universellen Seriellen Busses für Daten und Energie – Teil 1-2: Gemeinsame Komponenten – Festlegung für die USB-Stromversorgung (IEC 62680-1-2:2018)

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Interfaces bus série universel (USB) pour les données et l'alimentation électrique - Partie 1-2: Composants communs - Spécification USB pour la fourniture de courant (IEC 62680-1-2:2018)

Ta slovenski standard je istoveten z: EN IEC 62680-1-2:2018

ICS:

35.200	Vmesniška in povezovalna oprema	Interface and interconnection equipment
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en,fr,de

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EUROPEAN STANDARD
NORME EUROPÉENNE
EUROPÄISCHE NORM

EN IEC 62680-1-2

June 2018

ICS 29.220, 33.120, 35.200

Supersedes EN 62680-1-2:2017

English Version

**Universal Serial Bus interfaces for data and power - Part 1-2:
Common components - USB Power Delivery Specification
(IEC 62680-1-2:2018)**

Interfaces bus série universel (USB) pour les données et
l'alimentation électrique - Partie 1-2: Composants communs
- Spécification USB pour la fourniture de courant
(IEC 62680-1-2:2018)

Schnittstellen des Universellen Seriellen Busses für Daten
und Energie - Teil 1-2: Gemeinsame Komponenten -
Festlegung für die USB-Stromversorgung
(IEC 62680-1-2:2018)

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EN IEC 62680-1-2:2018 (E)**European foreword**

The text of document 100/2968/CDV, future edition 3 of IEC 62680-1-2, prepared by technical area 14: "Interfaces and methods of measurement for personal computing equipment", of IEC/TC 100: "Audio, video and multimedia systems and equipment" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 62680-1-2:2018.

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- latest date by which the document has to be (dop) 2019-02-17
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INTERNATIONAL STANDARD



**Universal serial bus interfaces for data and power –
Part 1-2: Common components – USB Power Delivery specification**

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This third edition cancels and replaces the second edition published in 2017 and constitutes a technical revision.

The text of this standard was prepared by the USB Implementers Forum (USB-IF). The structure and editorial rules used in this publication reflect the practice of the organization which submitted it.

The text of this International Standard is based on the following documents:

CDV	Report on voting
100/2968/CDV	100/3045/RVC

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

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The IEC 62680 series is based on a series of specifications that were originally developed by the USB Implementers Forum (USB-IF). These specifications were submitted to the IEC under the auspices of a special agreement between the IEC and the USB-IF.

This standard is the USB-IF publication USB Power Delivery Specification Revision 3.0 V.1.1 and ECNs through 12 June 2017.

The USB Implementers Forum, Inc.(USB-IF) is a non-profit corporation founded by the group of companies that developed the Universal Serial Bus specification. The USB-IF was formed to provide a support organization and forum for the advancement and adoption of Universal Serial Bus technology. The Forum facilitates the development of high-quality compatible USB peripherals (devices), and promotes the benefits of USB and the quality of products that have passed compliance testing.

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Universal Serial Bus Power Delivery Specification

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